



ANSYS Completes Latest Certification On TSMC 5nm FinFET Process Technology

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PITTSBURGH, April 22, 2019 /PRNewswire/ -- Through new certifications and a comprehensive suite of semiconductor design solutions, [TSMC](#) and [ANSYS](#) (NASDAQ: ANSS) empower mutual customers to meet increasing demands for next-generation of innovations in mobile, networking, 5G, artificial intelligence (AI), cloud and data center applications.

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Advancements in these cutting-edge applications are pushing the limits of performance within a power and thermal constrained environment. AI applications — including training and inferencing data sets in the cloud and edge — require power-hungry, high-performance processors with increased functionality.

TSMC certifies [ANSYS® RedHawk™](#) and [ANSYS® Totem™](#) multiphysics solutions on its latest 5nm FinFET process technology. The certifications include extraction, power integrity and reliability, signal electromigration (signal EM) and thermal reliability analysis, and statistical EM budgeting (SEB) analysis. Optimized for mobile and HPC applications, the certifications enable low power design solutions for TSMC's most advanced process technology.

"ANSYS' solutions are certified on TSMC industry-leading 5nm FinFET, 7nm, and 7nm FinFET Plus processes, enabling our mutual customers to verify and validate their designs with increased confidence to address growing performance, reliability and power challenges," said Suk Lee, senior director, design infrastructure management division at TSMC. "Our fruitful collaboration with ANSYS results in empowering customers to achieve their successes in high-growth markets with primary focuses on leading edge AI, data center, cloud and mobile applications."

"Multiphysics analysis enables silicon success for 7nm and below FinFET designs," said John Lee, general manager at ANSYS. "We are proud to collaborate with TSMC to enable our mutual customers to achieve their power, performance, area and reliability goals with our solutions."

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